Single Inverter, TTL Level

LSTTL-Compatible Inputs

The NLU1GT04 MiniGate $^{\text{m}}$ is an advanced CMOS high-speed inverting buffer in ultra-small footprint.

The device input is compatible with TTL-type input thresholds and the output has a full 5.0 V CMOS level output swing.

The NLU1GT04 input and output structures provide protection when voltages up to 7 V are applied, regardless of the supply voltage.

Features

- High Speed: $t_{PD} = 3.8 \text{ ns} (Typ) @ V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1 \ \mu A$ (Max) at $T_A = 25^{\circ}C$
- TTL–Compatible Input: $V_{IL} = 0.8 \text{ V}$; $V_{IH} = 2.0 \text{ V}$
- CMOS–Compatible Output:
 - $V_{OH} > 0.8 V_{CC}; V_{OL} < 0.1 V_{CC}$ @ Load
- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Ultra–Small Packages
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

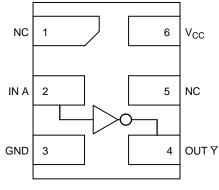


Figure 1. Pinout (Top View)

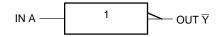
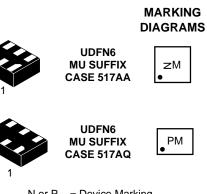


Figure 2. Logic Symbol



ON Semiconductor®

www.onsemi.com



N or P = Device Marking M = Date Code

PIN ASSIGNMENT

1	NC					
2	IN A					
3	GND					
4	OUT Y					
5	NC					
6	V _{CC}					

FUNCTION TABLE

A	Ϋ́
L	H
H	L

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit	
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V	
V _{IN}	DC Input Voltage		-0.5 to +7.0	V
V _{OUT}	DC Output Voltage		-0.5 to +7.0	V
Ι _{ΙΚ}	DC Input Diode Current	V _{IN} < GND	-20	mA
Ι _{ΟΚ}	DC Output Diode Current	V _{OUT} < GND	±20	mA
Ι _Ο	DC Output Source/Sink Current	±12.5	mA	
I _{CC}	DC Supply Current Per Supply Pin	±25	mA	
I _{GND}	DC Ground Current per Ground Pin	±25	mA	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
ΤL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
TJ	Junction Temperature Under Bias		150	°C
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating Oxygen	Index: 28 to 34	UL 94 V–0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body Machine Charged Device	> 2000 > 200 N/A	V	
ILATCHUP	Latchup Performance Above V _{CC} and Below GND at 12	25 °C (Note 5)	±500	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

2. Tested to EIA / JESD22-A114-A.

3. Tested to EIA / JESD22-A115-A.

4. Tested to JESD22-C101-A.

5. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V
V _{IN}	Digital Input Voltage	0	5.5	V
V _{OUT}	Output Voltage	0	5.5	V
T _A	Operating Free–Air Temperature	-55	+125	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0	100 20	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

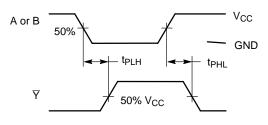
	Parameter	Conditions	V _{CC} (V)	T _A = 25 °C			T _A = +85°C		T _A = -55°C to +125°C		
Symbol				Min	Тур	Max	Min	Max	Min	Max	Uni
V _{IH}	Low-Level Input Voltage		1.8	1.2			1.2		1.2		V
			3.0	1.4			1.4		1.4		
			4.5 to 5.5	2.0			2.0		2.0		
VIL	Low-Level Input Voltage		1.8			0.3		0.3		0.3	V
			3.0			0.53		0.53		0.53	1
			4.5 to 5.5			0.8		0.8		0.8	
V _{OH}	High–Level Output Voltage	V _{IN} = V _{IH} or V _{IL} I _{OH} = -50 μA	3.0 4.5	2.9 4.4	3.0 4.5		2.9 4.4		2.9 4.4		V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -2 \text{ mA}$ $I_{OH} = -4 \text{ mA}$ $I_{OH} = -8 \text{ mA}$	1.8 3.0 4.5	1.40 2.58 3.94			1.38 2.48 3.80		1.37 2.34 3.66		
V _{OL}	Low–Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50 \ \mu\text{A}$	3.0 4.5		0 0	0.1 0.1		0.1 0.1		0.1 0.1	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 2 \text{ mA}$ $I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$	1.8 3.0 4.5			0.36 0.36 0.36		0.44 0.44 0.44		0.52 0.52 0.52	
I _{IN}	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I _{CC}	Quiescent Supply Current	$0 \le V_{IN} \le V_{CC}$	5.5			1.0		20		40	μΑ
I _{CCT}	Quiescent Supply Current	V _{IN} = 3.4 V	5.5			1.35		1.50		1.65	mA
I _{OPD}	Output Leakage Current	V _{OUT} = 5.5 V	0.0			0.5		5.0		10	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

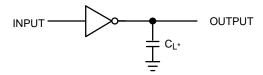
AC ELECTRICAL CHARACTERISTICS (Input $t_{\textrm{F}}$ = $t_{\textrm{f}}$ = 3.0 ns)

		V _{CC}	Test		T _A = 25 °C	;	TA = -	⊦85°C	T _A = -5 +12	55°C to 5°C	
Symbol	Parameter	(V)	Condition	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} ,	Propagation De-	3.0 to	C _L = 15 pF		5.0	10.0		11.0		13.0	ns
t _{PHL}	lay, Input A to Output Y	3.6 4.5 to	C _L = 50 pF		6.2	13.5		15.0		17.5	
			C _L = 15 pF		3.8	6.7		7.5		8.5	
		5.5	C _L = 50 pF		4.2	7.7		8.5		9.5	
C _{IN}	Input Capacitance				5	10		10		10.0	pF
C _{PD}	Power Dissipation Capacitance (Note 6)	5.0			10						pF

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no-load dynamic power consumption: $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.







*Includes all probe and jig capacitance. A 1–MHz square input wave is recommended for propagation delay tests.

Figure 4. Test Circuit

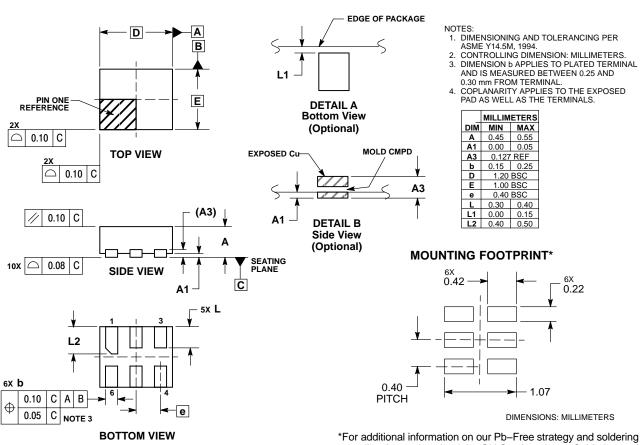
ORDERING INFORMATION

Device	Package	Shipping [†]
NLU1GT04MUTCG	UDFN6 (Pb-Free)	3000 / Tape & Reel
NLU1GT04AMUTCG	UDFN6 (Pb–Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

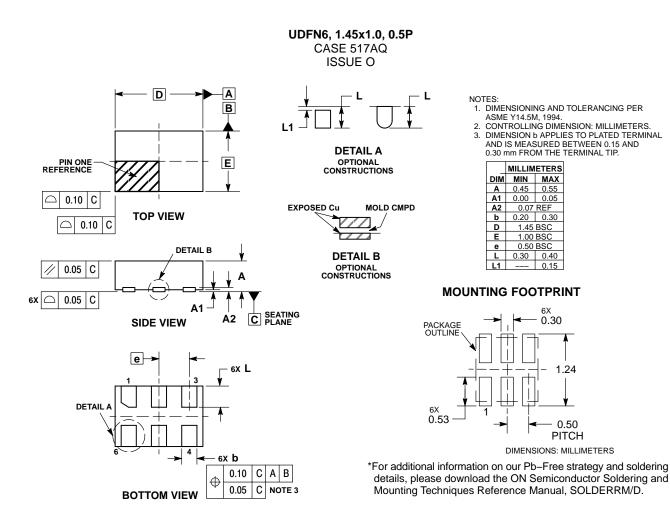
PACKAGE DIMENSIONS

UDFN6, 1.2x1.0, 0.4P CASE 517AA ISSUE D



details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS



MiniGate is a trademark of Semiconductor Components Industries, LLC (SCILLC).

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights or the rights of others. ON Semiconductor and tesigned, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconducts harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2010

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative